

Nobuhiko Nakano

List of Publications by Year in descending order

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27
papers

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citations

1307594

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27
docs citations

27
times ranked

173
citing authors

#	ARTICLE	IF	CITATIONS
1	The effect of topographical local charging on the etching of deep-submicron structures in SiO ₂ as a function of aspect ratio. Applied Physics Letters, 2001, 78, 883-885.	3.3	80
2	Effect of O ₂ plasma on plasma structures in oxygen radio frequency discharges. Journal of Applied Physics, 1996, 80, 6142-6147.	2.5	77
3	O ₂ rf discharge structure in parallel plates reactor at 13.56 MHz for material processing. Journal of Applied Physics, 1995, 77, 6181-6187.	2.5	65
4	Electron transport to a substrate in a radio frequency capacitively coupled plasma by the Boltzmann equation. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1998, 16, 294-299.	2.1	11
5	Bifacial PERC Solar Cell Designs: Bulk and Rear Properties and Illumination Condition. IEEE Journal of Photovoltaics, 2020, 10, 1538-1544.	2.5	11
6	The piezoresistive mobility modeling for cubic and hexagonal silicon carbide crystals. Journal of Applied Physics, 2020, 127, .	2.5	9
7	Optimization of Front Diffusion Profile in Bifacial Interdigitated Back Contact Solar Cell. IEEE Journal of Photovoltaics, 2020, 10, 1582-1590.	2.5	7
8	Bifacial Heterojunction Back Contact Solar Cell: 29-mW/cm ² Output Power Density in Standard Albedo Condition. IEEE Transactions on Electron Devices, 2021, 68, 5645-5651.	3.0	5
9	Area-efficient cross-coupled charge pump for on-chip solar cell. , 2016, , .		4
10	Comparison of thermal stress concentration and profile between power cycling test and thermal cycling test for power device heat dissipation structures using Ag sintering chip-attachment. , 2016, , .		4
11	Numerical simulation of the piezoresistive effect of $\hat{\Gamma}^2\text{Ga}_{2\text{O}_3}$ in the $\hat{\Gamma}^2\text{Ga}_{2\text{O}_3}$ direction. Japanese Journal of Applied Physics, 2021, 60, SCCL05.	1.5	4
12	Advanced Industrial Tunnel Oxide Passivated Contact Solar Cell by the Rear-Side Local Carrier-Selective Contact. IEEE Transactions on Electron Devices, 2022, 69, 2481-2487.	3.0	4
13	Design and Evaluation of Filterless RGB Sensor on Standard CMOS Process. IEEE Photonics Journal, 2022, 14, 1-7.	2.0	4
14	Stress and strain analysis using multi-physics solver for power device heat dissipation structures under thermal cycling test. , 2015, , .		3
15	Heterogeneous Integration of Boost Power Supply and On-Chip Solar Cell using triple well CMOS Process. IEJ Transactions on Electronics, Information and Systems, 2018, 138, 41-49.	0.2	3
16	Impact Ionization and Critical Electric Field in $\hat{\Gamma}^2\text{Ga}_{2\text{O}_3}$ -Oriented $\hat{\Gamma}^2\text{Ga}_{2\text{O}_3}$ Schottky Barrier Diode. IEEE Transactions on Electron Devices, 2022, 69, 3068-3072.	3.0	3
17	Transparent Conductive Oxide Materials for Bifacial Heterojunction Back Contact Solar Cells. IEEE Transactions on Electron Devices, 2022, 69, 3748-3752.	3.0	2
18	Thermal stress analysis under thermal cycling test for SiC power device heat dissipation structures using Ag sintered layer. , 2017, , .		1

#	ARTICLE	IF	CITATIONS
19	Prototype and measurement of automatic synchronous PLL system for N-path filter for hum noise reduction. , 2017, , .		1
20	Piezoresistive Thermal Characteristics of Aluminum-Doped P-Type 3C-Silicon Carbides. IEEE Journal of the Electron Devices Society, 2022, 10, 547-553.	2.1	1
21	A design of Transimpedance Amplifier using OTA as a feedback resistor for patch-clamp measurement system. , 2015, , .		0
22	Design of low power single stage CMOS complementary regulated cascode distributed amplifier based on inductive coupling technique. , 2015, , .		0
23	Stress Concentration and Profile under Thermal Cycling Test in Power Device Heat Dissipation Structures Using Double-Side Chip Bonding with Ag Sintered Layer on Cu Plate. , 2016, , .		0
24	Warping and Thermal Stress under Thermal Cycling Test in SiC and Si Power Device Structures Using Direct Chip-Bonding with Ag Sintered Layer on Cu Plate. , 2018, , .		0
25	Multi Channel Low-Noise Low-Power Amplifier for Neural Signal Acquisition. IEEJ Transactions on Electronics, Information and Systems, 2015, 135, 2-11.	0.2	0
26	Design of Solar Cell for Micro System Using Standard CMOS Process. IEEJ Transactions on Sensors and Micromachines, 2019, 139, 252-257.	0.1	0
27	An On-Chip Self-Powered Non-Volatile One-Time-Programmable Memory System in Standard CMOS Technology. , 2020, , .		0